

Weidmüller Interface GmbH & Co. KG Klingenbergstraße 26 D-32758 Detmold Germany

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Product image





Similar to illustration

OMNIMATE Power BV / SV 7.62HP – the 28 kVA performance class

Tailor-made solutions for high performers

More power reserves for higher load bearing capacity: The OMNIMATE Power BV / SV 7.62HP is the middleclass of the power connector systems. It has a large clamping capacity, high overload resistance and the largest range of variants and accessories to choose from: the high performer of the HP range. HP means High Performance – this performance covers a great deal: the full rated current up to 50°C without derating, unlimited 600-V approval according to UL, and the additional finger safety for 400 V-TN systems (+ 3.0 mm) in compliance with the application directive IEC 61800-5-1.

General ordering data

Version	PCB plug-in connector, male header, Screw flange, THT/THR solder connection, 7.62 mm, Number of poles: 3, 90°, Solder pin length (I): 2.6 mm, tinned, black, Tape
Order No.	<u>2545950000</u>
Туре	SV-SMT 7.62HP/03/90SF 2.6SN BK RL
GTIN (EAN)	4050118555882
Qty.	110 pc(s).
Product data	IEC: 1000 V / 41 A
	UL: 300 V / 40.5 A
Packaging	Таре

Creation date March 29, 2021 7:10:20 PM CEST



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Technical data

Depth	28.3 mm	Depth (inches)	1.114 inch
Height of lowest version	11.4 mm	Net weight	6.6 g
System specifications			
Product family	OMNIMATE Power - series BV/SV 7.62HP	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	7.62 mm
Pitch in inches (P)	0.3 inch	Outgoing elbow	90°
Number of poles	3	Number of solder pins per pole	2
Solder pin length (I)	2.6 mm	Solder pin length tolerance	+0.1 / -0.3 mm
Solder pin dimensions	0.8 x 1.0 mm	Solder eyelet hole diameter (D)	1.4 mm
Solder eyelet hole diameter tolera	nce (D)+ 0,1 mm	L1 in mm	15.24 mm
L1 in inches	0.6 inch	Number of rows	1
Pin series quantity	1	Touch-safe protection acc. to DIN VDE 57 106	safe to back of hand above the printed circuit board
Touch-safe protection acc. to DIN	VDE	Volume resistance	
0470	IP 20		2.00 mΩ
Tightening torque for screw flange	e, min. 0.2 Nm	Tightening torque for screw flange, max	κ. 0.3 Nm
Plugging force/pole, max.	12 N	Pulling force/pole, max.	7 N

Insulating material	PA GF HT3	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	1
Comparative Tracking Index (CTI)	≥ 600	Moisture Level (MSL)	3
UL 94 flammability rating	V-0	Contact material	Copper alloy
Contact surface	tinned	Layer structure of solder connection	13 µm Ni / 46 µm Sn matt
Layer structure of plug contact	13 µm Ni / 46 µm Sn matt	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	130 °C	Temperature range, installation, min.	-25 °C
Temperature range, installation, max.	130 °C		

Rated data acc. to IEC

tested acc. to standard		Rated current, min. number of poles	
	IEC 60664-1, IEC 61984	(Tu=20°C)	41 A
Rated current, max. number of poles (Tu=20°C)	41 A	Rated current, min. number of poles (Tu=40°C)	41 A
Rated current, max. number of poles (Tu=40°C)	41 A	Rated voltage for surge voltage class / pollution degree II/2	1,000 V
Rated voltage for surge voltage class / pollution degree III/2	630 V	Rated voltage for surge voltage class / pollution degree III/3	630 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	6 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	6 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	6 kV	Short-time withstand current resistance	3 x 1s with 420 A

Technical data



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Rated data acc. to UL 1059

Institute (cURus)

c Rus
300 V
300 V
40.5 A
6.9 mm
Specifications are

maximum values, details see approval certificate.

Certificate No. (cURus)

	E60693
Rated voltage (Use group C / UL 1059)	300 V
Rated current (Use group B / UL 1059)	40.5 A
Rated current (Use group D / UL 1059)	10 A
Creepage distance, min.	9.6 mm

Packing

Packaging	Таре	VPE length	0
VPE width	0	VPE height	0
Tape depth (T2)	15.8 mm	Tape width (W)	56 mm
Tape pocket depth (K0)	15.3 mm	Tape pocket height (A0)	28.4 mm
Tape pocket width (B0)	39.06 mm	Tape pocket separation (P1)	36 mm
Tape hole separation (E)	1.75 mm	Tape pocket separation (F)	26.2 mm
Tape reel diameter Ø (A)	330 mm	Surface resistance	$Rs = 10^9 - 10^{12} \Omega$

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	Additional colours on request
	Rated current related to rated cross-section & min. No. of poles.
	• P on drawing = pitch
	 Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.
	• Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months
Approvals	
A	
Approvals	c Tus

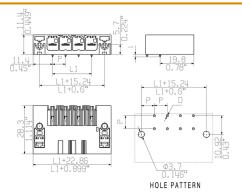
UL File Number Search

υ E60693

Creation date March 29, 2021 7:10:20 PM CEST

Drawings

Dimensional drawing

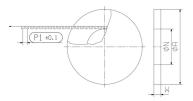




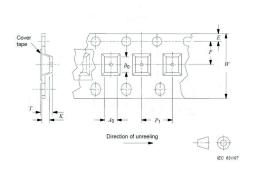
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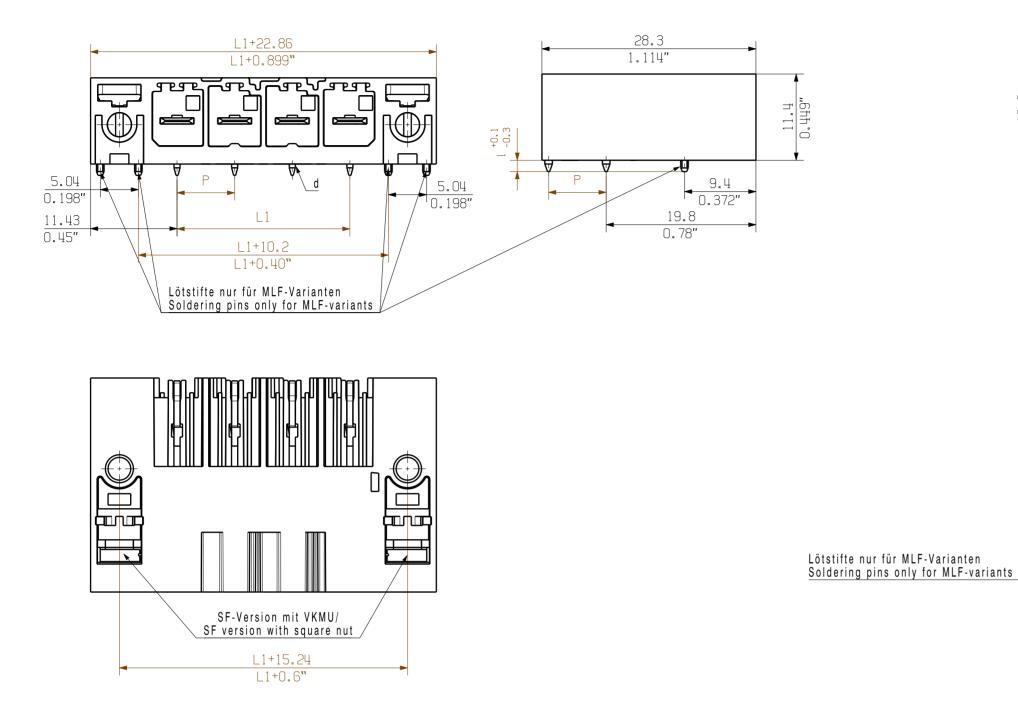
Germany



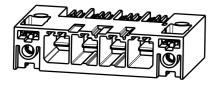
Dimensional drawing



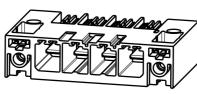
<u>SV-SMT 7.62HP/04/90(S/L)F</u>



SV-SMT 7.62HP/04/90F



SV-SMT 7.62HP/04/90SF

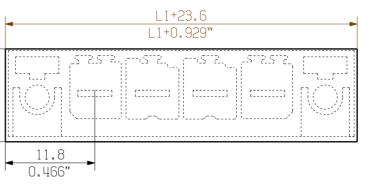


SV-SMT 7.62HP/04/90LF



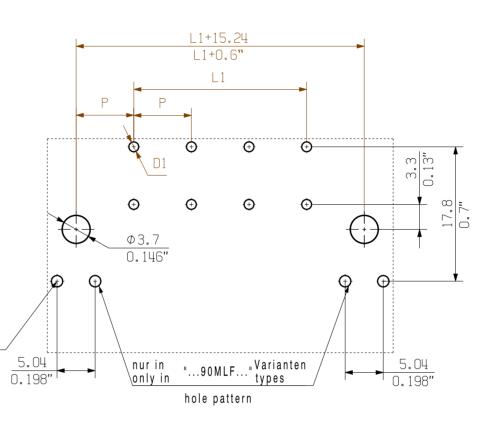
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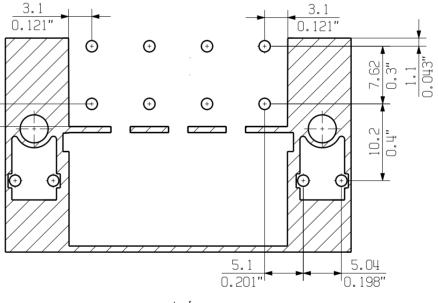
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12.3 0.483"

min.front plate cut out





paste free area max. dimension

							10	68.58	2.7
							9	60.96	2.4
							8	53.34	2.1
							7	45.72	1.8
							6	38.10	1.5
P = Ra	aster / pitch 7.62					1.5	5	30.48	1.2
D = Ø1	.4+0.1/-0.05					2.6	4	22.86	0.9
d = 0.8						3.5	3	15.24	0.6
						5.5	2	7.62	0.3
							no of	L1	L1
	L TOLERANCE: 2768-m					[mm]	poles	[mm]	
DIN ISO				Prim PLM	Part No.: 225880			[m m]	[inch]
	2768-m	Max. nos				Prim	poles ERP Part No.: 63450	[mm] : 249955	[inch] 0000 4
DIN ISO	2768-m EC00002212		ication		Part No.: 225880	Prim	poles ERP Part No.:	[mm] : 249955	[inch] 0000 4 Issue n
DIN ISO	2768-m EC00002212 First Issue Date					Prim	poles ERP Part No.: 63450 Drawing no.	[mm] : 249955	[inch] 0000 4 Issue n
DIN ISO	2768-m EC00002212 First Issue Date		ication	We	eidmülle	Prim Pr	poles ERP Part No.: 6 3 4 5 0 Drawing no. Sheet 12	[mm] : 2499555	[inch] 0000
DIN ISO	2768-m EC00002212 First Issue Date	Modif	Date 30.08.2019	We Name	eidmülle	Prim Prim	poles ERP Part No.: 6 3 4 5 0 Drawing no. Sheet 12 /IT//90/27	[mm] : 2499555	[inch] 0000 4 Issue n
DIN ISO	2768-m EC00002212 First Issue Date 14.11.2016	Modif Drawn Responsible	Date 30.08.2019	Name Helis, Maria	eidmülle	Prim Pr	poles ERP Part No.: 6 3 4 5 0 Drawing no. Sheet 12 /IT//90/27 EISTE	[mm] : 2499555	[inch] 0000 4 Issue n

For the mounting of PCBs, it should be noted that the rated data relates only to the PCB components alone.

The neccessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to IEC 664 / VDE 0110. The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application. Provided that the components are used to the intended purpose, all requirements with respect to the occuring of electrical, mechanical, thermic and corrosive stress will be satisfied.

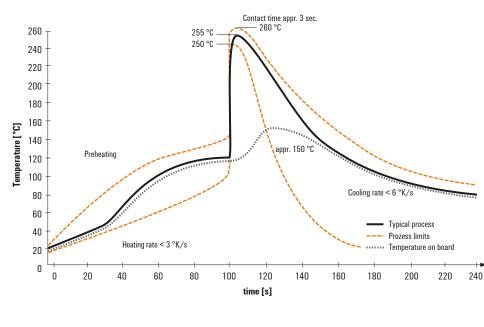
Wave Solder Profile

Recommended wave solderding profiles

Weidmüller 🟵

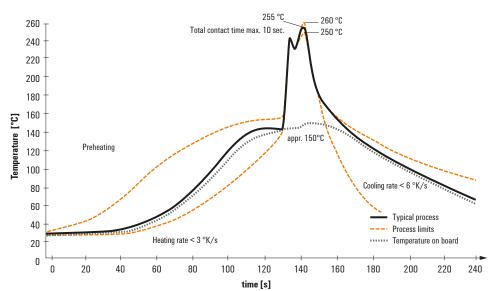
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Double Wave:

Single Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

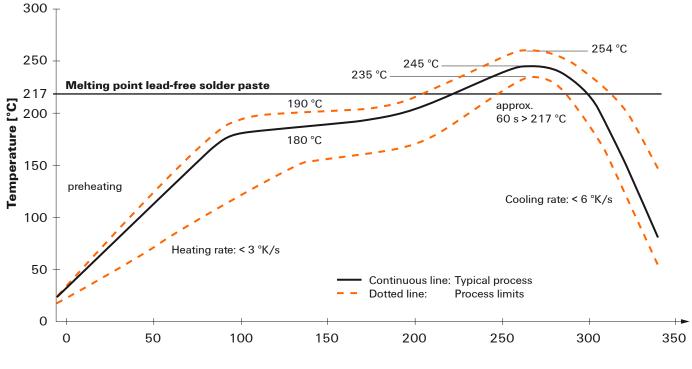
Reflow Solder Profile

Recommended reflow soldering profile



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Time [sec]

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.